

Product Change Notification - LIAL-26WMMN354

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Date:

29 Mar 2018

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers

Affected CPNs:**Notification subject:**

CCB 3317 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) wire in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

Notification text:**PCN Status:**

Initial Notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

Pre Change:

Using gold (Au) bond wire and G600 mold compound material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and G700LS mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Wire material	Au	CuPdAu
Die attach material	8290	8290
Molding compound material	G600	G700LS
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	March 2018					-->	August 2018					
	09	10	11	12	13		31	32	33	34	35	
Workweek												
Initial PCN Issue Date					X							
Qual Report Availability								X				

Final PCN Issue Date									X	
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Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

March 29, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-26WMMN354_QUAL_PLAN.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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